

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A printed-wiring substrate comprising:

a molded insulating substrate serving as a support;

a conductor layer formed on the insulating substrate; and

a capacitor element embedded in the insulating substrate and connected to the conductor layer, wherein

the printed-wiring substrate is adapted for mounting an integrated-circuit element thereon connecting to the conductor layer, characterized in that

the insulating substrate is molded by placing the capacitor element in a predetermined mold and charging resin into the mold, and

the capacitor element has roughened side surfaces to increase the adhesion strength between the capacitor element and resin charged into the mold.
2. (original): The printed-wiring substrate according to claim 1, wherein the insulating substrate includes a reinforcement member embedded in the insulating substrate.

3. (original): The printed-wiring substrate according to claim 2, wherein the insulating substrate includes, as the reinforcement member, glass cloth embedded in the insulating substrate.

4. (withdrawn): The printed-wiring substrate according to claim 2, wherein the insulating substrate includes, as the reinforcement member, a metal plate embedded in the insulating substrate.

5. (original): The printed-wiring substrate according to claim 1, wherein the insulating substrate has through holes and through-hole conductors formed on wall surfaces of the through holes.

6. (original): The printed-wiring substrate according to claim 1, wherein the capacitor element has terminals on each of upper and lower surfaces thereof; and the terminals on the upper surface are exposed from an upper surface of the insulating substrate, and the terminals on the lower surface are exposed from a lower surface of the insulating substrate.

7. (currently amended): The printed-wiring substrate according to claim 6, further comprising at least one insulating layer formed on each of the upper and lower surfaces of the insulating substrate and at least one conductor layer formed on the insulating layer, wherein the

conductor layer is connected to the terminals of the capacitor element or the through-hole conductors by vias formed in the insulating layer.

8. (canceled)

9. (withdrawn - currently amended): A method for fabricating a printed-wiring substrate including an insulating substrate formed of resin and serving as a support, a conductor layer formed on the insulating substrate, and a capacitor element connected to the conductor layer comprising:

a molded insulating substrate serving as a support;

a conductor layer formed on the insulating substrate; and

a capacitor element embedded in the insulating substrate and connected to the conductor layer, wherein

the printed-wiring substrate is adapted for mounting an integrated-circuit element thereon connecting to the conductor layer, characterized in that

the insulating substrate is molded by placing the capacitor element in a predetermined mold and charging resin into the mold, and

the capacitor element has roughened side surfaces to increase the adhesion strength between the capacitor element and resin charged into the mold, the method comprising:

roughening at least side surfaces of the capacitor element;

placing the capacitor element having roughened side surfaces in a mold and charging resin into the mold to thereby mold the insulating substrate;

exposing terminals of the capacitor element to the outside of the insulating substrate; and

forming a conductor layer on the insulating substrate such that the conductor layer is connected to the terminals of the capacitor element exposed to the outside of the insulating substrate.

10. (withdrawn): The method for fabricating a printed-wiring substrate according to claim 9, wherein said charging comprises a plurality of charging operations, and between subsequent charging operations, disposing a sheet of glass cloth on a resin layer formed within the mold to form layers of the resin and the layer of glass cloth alternately stacked in the thickness direction.

11. (withdrawn): The method for fabricating a printed-wiring substrate according to claim 9, wherein said charging comprises a plurality of charging operations, and between subsequent charging operations, disposing a metal plate on a resin layer formed within the mold to form layers of the resin and the metal plate alternately stacked in the thickness direction.

12. (canceled)

13. (canceled)

AMENDMENT UNDER 37 C.F.R. § 1.111
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14. (canceled)